

# The Magic Square of IoT



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# Agenda

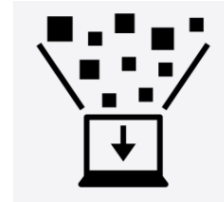
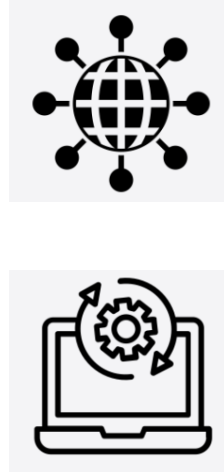
- Introduction
- The Corners of the Square
- Inter-dependencies
- Example
- Summary



# What is IoT?

## 3 Main Characteristics:

- Connectivity
- Data Collection
- Data Processing



1982                      1999                      2000s                      2010s                      2020 and beyond

## Mile Stones

Modified Coke  
machine report  
inventory

First mention  
Internet of  
Things

RFID & Sensor,  
Growth in  
Wireless Tech

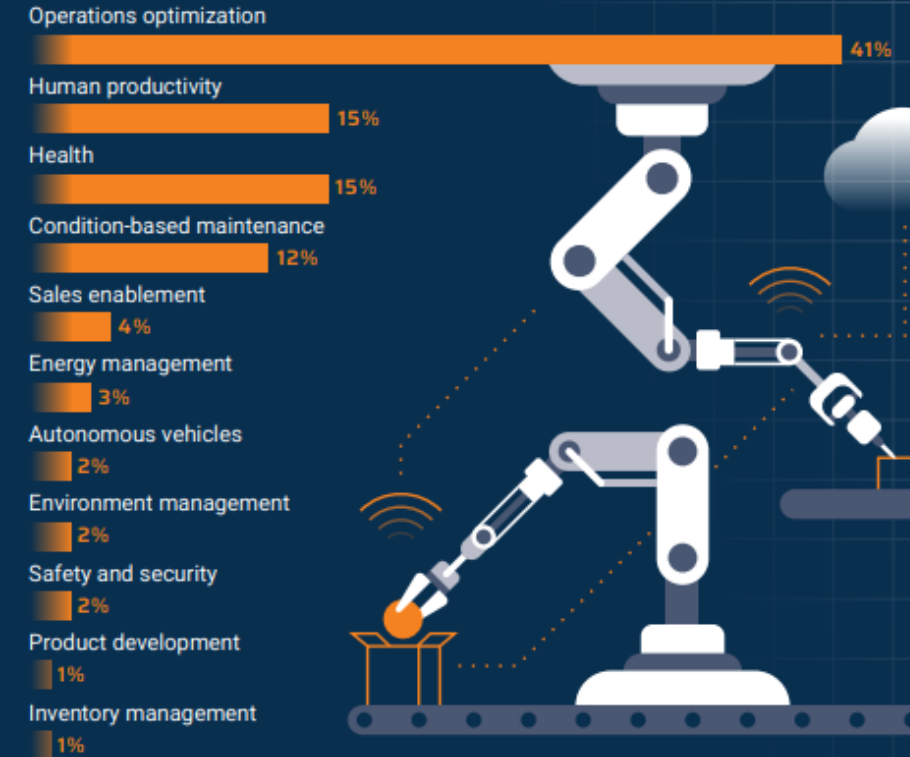
SmartX, Consumer  
IoT, IIoT,  
Standardization  
efforts (5G)

Edge computing,  
AI,  
Part of 5G,  
...

## Operations optimization as key value of IoT in 2030

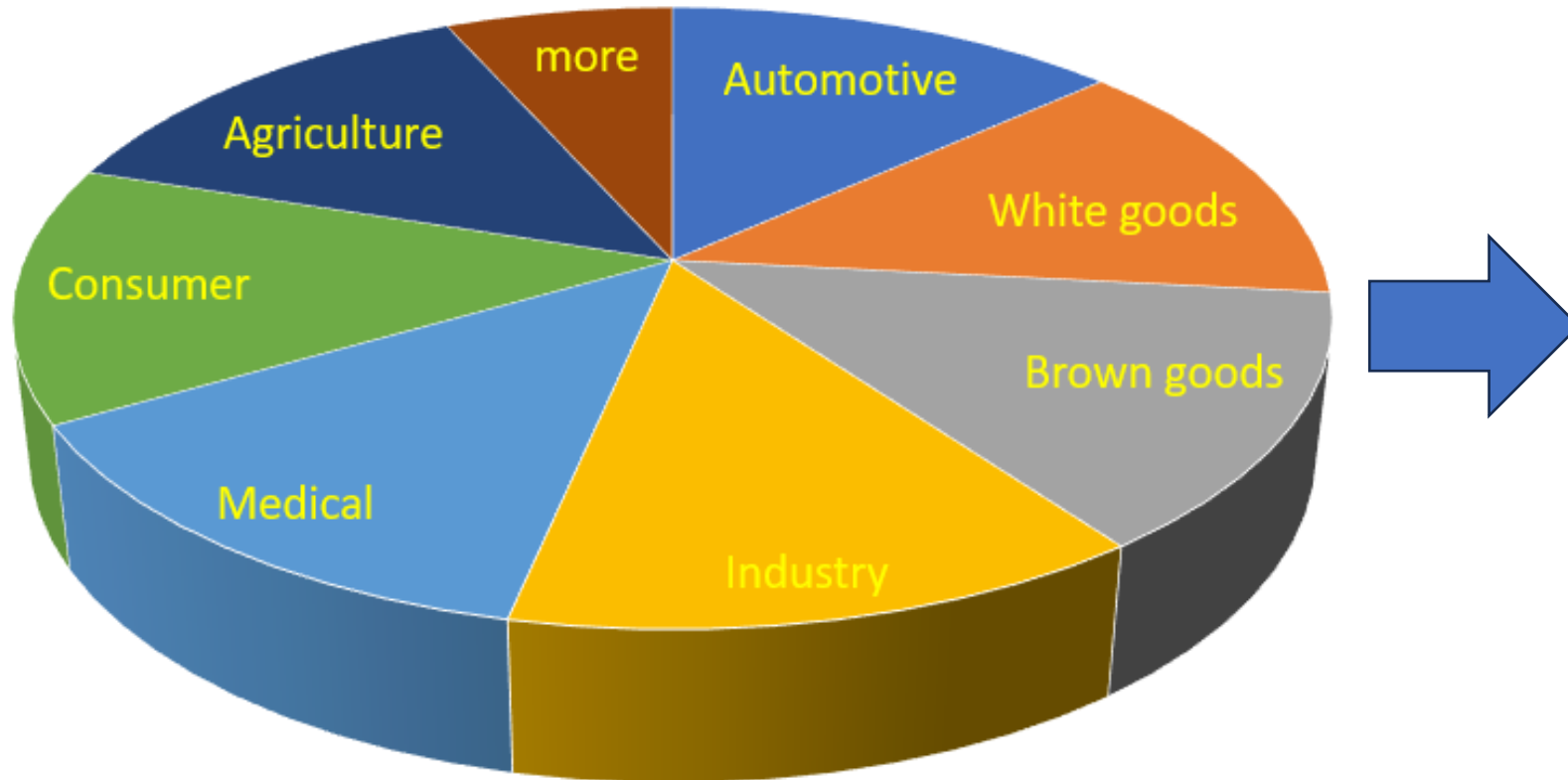
The largest share of the estimated economic value of IoT worldwide in 2030 is expected to be generated through operations optimization.

### GLOBAL DISTRIBUTION OF ECONOMIC VALUE OF IOT IN 2030, BY USE CASE CLUSTER



Source: McKinsey, The Internet of Things 2022

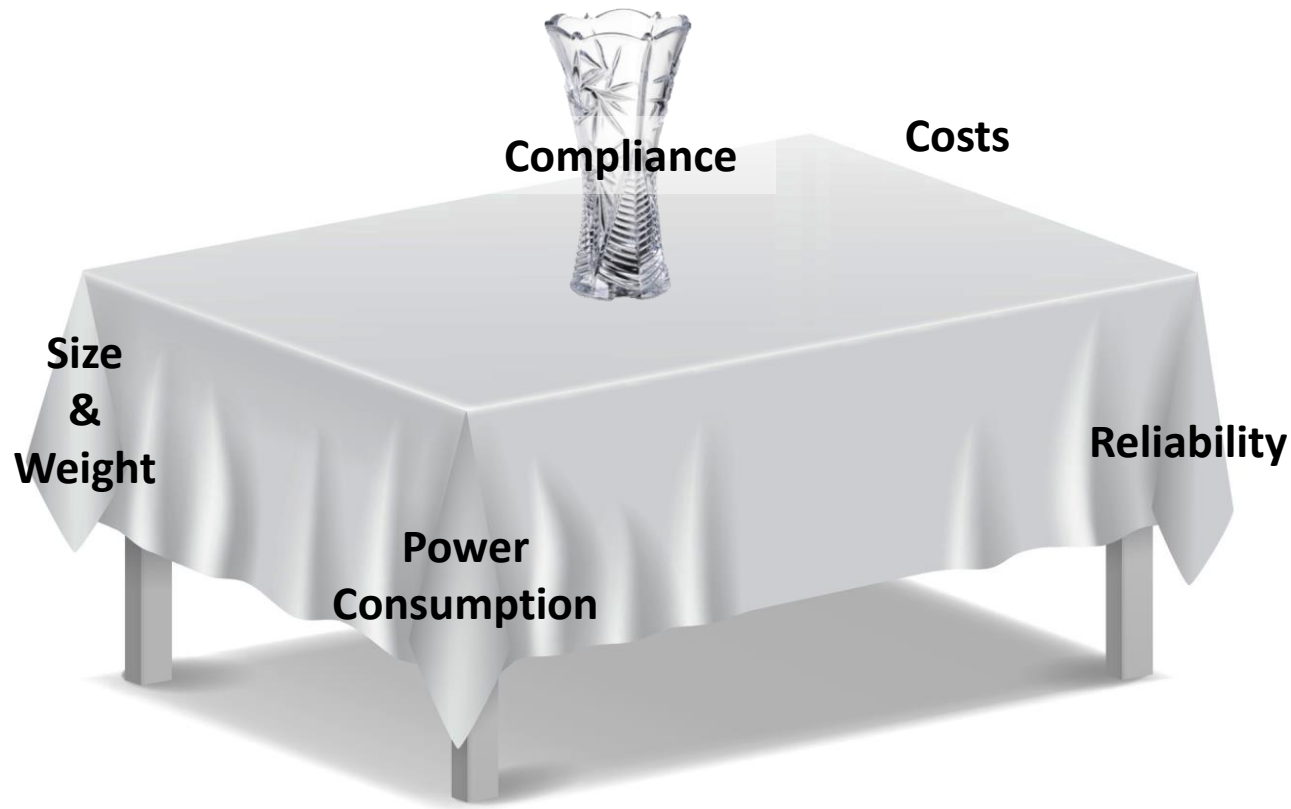
# Focus Area for this Presentation



Focus on devices which have:

- **Wireless connectivity**
- **Limited availability of Power**
- **Requirement for Limited space and limited weight**
- **Cost pressure**

# The Corners of the Square



- **Power Consumption**
  - Battery powered devices
- **Reliability**
  - Critical Environment
- **Size & Weight**
  - Wearables
- **Costs**
  - Mass products
- **Compliance**
  - ALL areas

# Measures to improve Power Consumption

- Wireless Communication Standards
- Power Converter Efficiency
  - Selected Topology
  - Use of High-Quality Components
  - Optimize Switching Frequency
  - Implement advanced Semiconductors
- Microcontroller Operation
- Standby-Power / Deep-Sleep
- Temperature Control



# Measures to improve Reliability

- Use of High-Quality Components
- Predictive Maintenance
- Battery Technology
- Energy Harvesting
- Type of connectivity



# Measures to improve Size & Weight

- Smaller Components
- SoC (System on a Chip) / Stacked Components
- Thin-Film / Flexible Electronics
- Optimize Efficiency
- Smaller Heat sink
- Smaller Battery
- Energy Harvesting -> substitute battery
- Use advanced material
- External Antenna



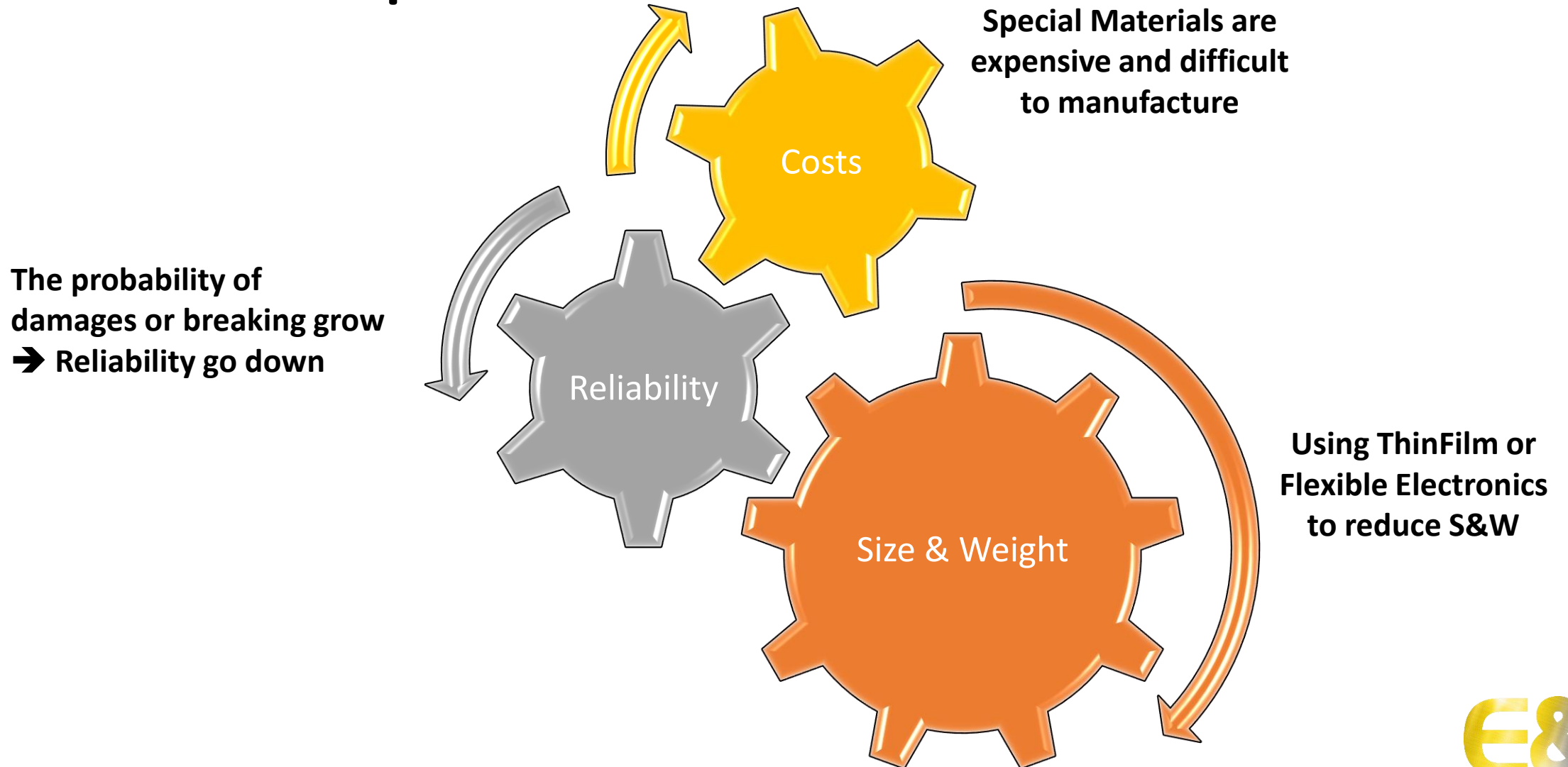


# Measures to improve Cost

- Cost optimized Component sourcing
- Cost optimized Technologies
- Housing (Metal vs. plastic)
- Standardization
- Production automation and outsourcing
- Modular Design for easy Scaling / Function adaption



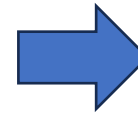
# Mutual Impact



# Detailed Example Power Consumption

Optimizing Power consumption by increasing the converter efficiency.

1. Implement GaN-based switches



- Higher Energy efficiency (up to 80% lower losses)
- Higher Power density
- Higher Temperature sustainability
- Higher Switching speed

2. Select high quality Components

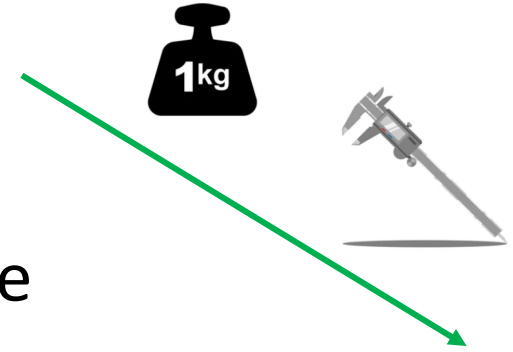


**Direct  
impact  
on COST**

**Impact  
on COST?**

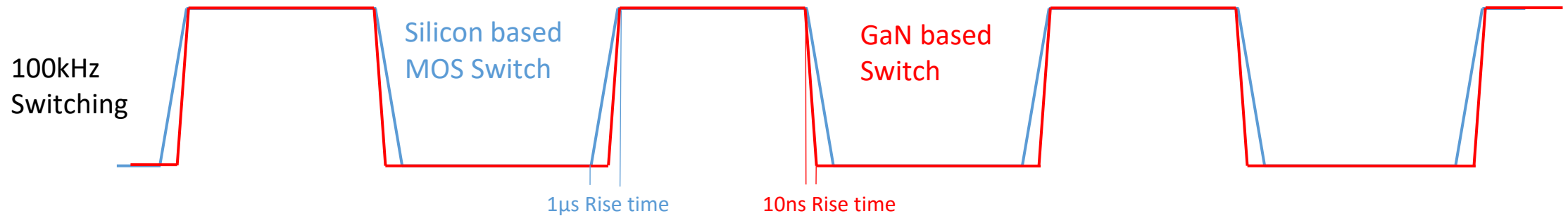
# Using GaN → Effect on Size & Weight

- Lower losses allow smaller heat sink
- Lower losses allow smaller battery
- Higher Power density allow do downsize switch device
- Higher Switching Frequency allow smaller components like Inductivity



→ Direct impact on COST

# Possible Effect on Compliance

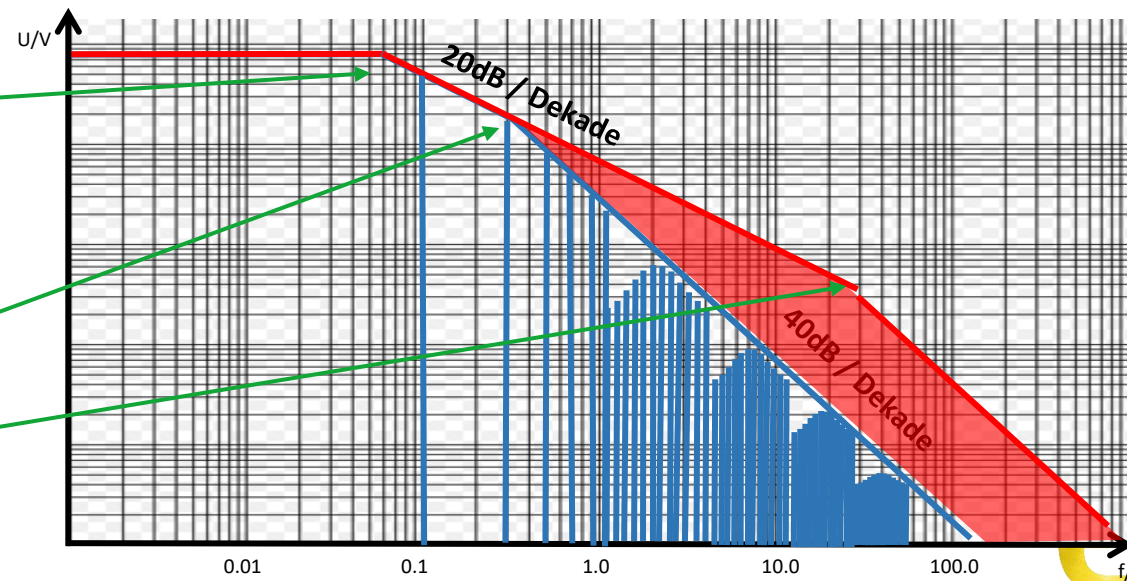


- 1<sup>st</sup> Frequency point =  $\frac{2 * f_{sw}}{\pi}$   
(here = 63.7kHz)

- 2<sup>nd</sup> Frequency point =  $\frac{1}{\pi * RiseTime}$

1µs Rise Time      => 318,3kHz

10ns Rise Time      => 31,83MHz



# Possible Effect on Compliance

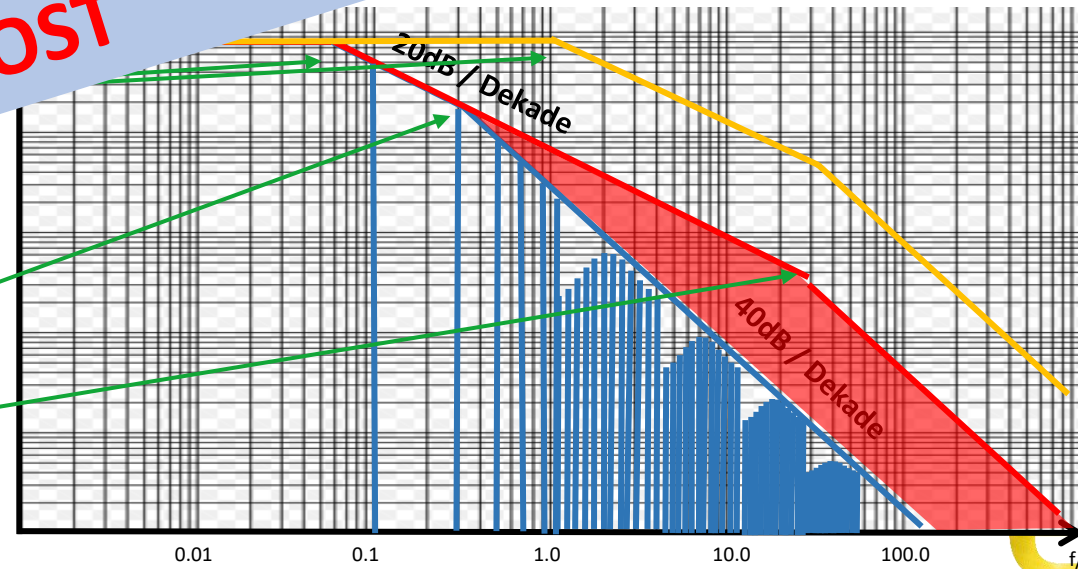
2MHz Switching



Dealing with this issue cost time and possibly new Filter  
 → Effect on COST

- 1<sup>st</sup> Frequency point =  $\frac{2}{\pi * RiseTime}$   
 (here = 637kHz)
- 2<sup>nd</sup> Frequency point =  $\frac{2}{\pi * RiseTime}$

1μs Rise Time           ⇒ 318,3kHz  
 10ns Rise Time        ⇒ 31,83MHz



# Effect on Reliability

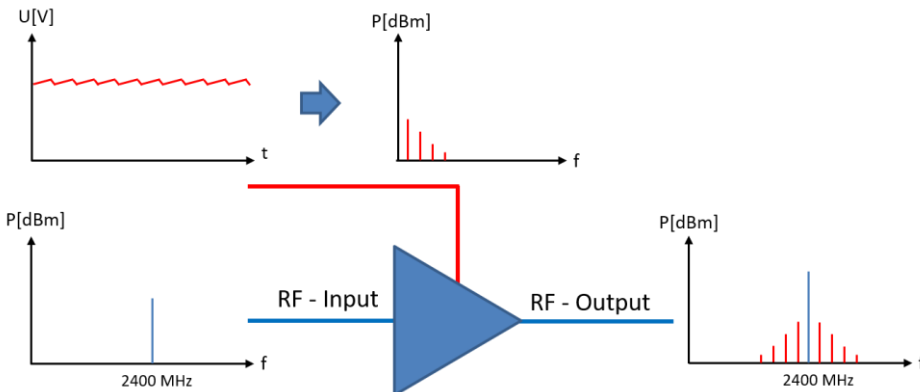
- GaN devices increase reliability
- Lower power consumption -> extend lifetime
- Improper design can harm RF performance
  - EMI interference with Carrier
  - Ripple introduced interference



**Direct  
impact  
on COST**



**Direct  
impact  
on COST**



# Summary Effect on Cost

- Higher quality component increase cost
- GaN is still a bit more expensive than Silicon
- Optimizing effort adds labour cost
- Working with GaN requires higher performance T&M equipment
  
- Smaller heat sinks are cheaper
- Higher Efficiency allows smaller battery
- Higher Reliability lowers Service costs





- **Compliance is non negotiable**
- **There are 4 Core Requirements**
- **Every Area of Application has different priorities on requirements**
- **Any change on any of these 4 Requirement impact the other 3 (positive & negative)**
- **Keep an eye on each Parameter**

# Thank you!

**Booth Number: 7F050**

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